

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	("5753353"   "6008110").PN.	US-PGPUB; USPAT	OR	ON	2008/04/18 13:29
S2	6	("6008110").URPN.	USPAT	OR	ON	2008/04/18 13:40
S3	6	("6008110").URPN.	USPAT	OR	ON	2008/04/18 15:48
S4	97	(boron with dop\$3 with silicon) and getter\$3 and (hydrogen with anneal\$3)	US-PGPUB; USPAT	OR	ON	2008/04/18 15:55
S5	18	S4 and (SOI with substrate)	US-PGPUB; USPAT	OR	ON	2008/04/18 15:56
S6	1	("20010029072").PN.	US-PGPUB; USPAT	OR	OFF	2008/04/18 17:32
S7	9	Toshiro.IN. and SOI	US-PGPUB; USPAT	OR	ON	2008/10/17 16:45
S8	121	SOI and implant\$5 and ((support or handle) with wafer) and cleav\$3	USPAT	OR	ON	2009/04/03 11:16
S9	1686458	SOI and implant\$5 and ((support or handle) with wafer) and cleav\$3 and ((support or handle) with wafer with boron)I	USPAT	OR	ON	2009/04/03 11:20
S10	1686458	SOI and implant\$5 and ((support or handle) with wafer) and cleav\$3 and ((support or handle) with boron with dop\$3)I	USPAT	OR	ON	2009/04/03 11:21
S11	0	SOI and implant\$5 and ((support or handle) with wafer with boron) and cleav\$3	USPAT	OR	ON	2009/04/03 11:21
S12	0	SOI and implant\$5 and ((support or handle) with wafer with boron) and cleav\$3	USPAT	OR	ON	2009/04/03 11:22

S13	12	SOI and implant\$5 and ((support or handle) with wafer with boron)	USPAT	OR	ON	2009/04/03 11:22
S14	13	Kub.IN. and SOI	USPAT	OR	ON	2009/04/03 11:32
S15	8	Usenko.IN. and SOI	USPAT	OR	ON	2009/04/03 11:33
S16	3758	438/455,458.ccls. or 257/E21.568.ccls.	US-PGPUB; USPAT	OR	ON	2009/12/23 12:49
S17	3112	438/455,458.ccls.	US-PGPUB; USPAT	OR	ON	2009/12/23 13:09
S18	1252	257/E21.568.ccls.	US-PGPUB; USPAT	OR	ON	2009/12/23 14:04
S19	686	S16 and (thickness with SOI)	US-PGPUB; USPAT	OR	ON	2009/12/23 14:58

### EAST Search History (I nterference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	(boron and (wafer or substrate) and (SOI or (silicon\$on \$insulat\$3) or (silicon with on with insulat\$3)) and implant\$3 and hydrogen and (active or device) and bond\$3 and (heat\$3 or anneal \$3) and thick\$4). CLM.	US-PGPUB; UPAD	OR	ON	2009/12/24 12:36

12/ 24/ 2009 12:38:43 PM

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